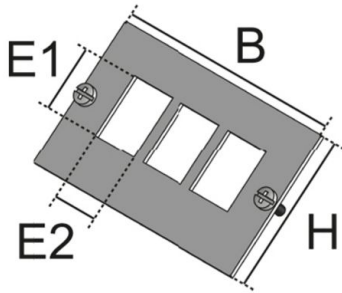


UDEP AMP

installation board, data technology

Installation board made of aluminium, coated black. To be screwed into a data device carrier. For data jacks.



material	Aluminium, coated black on one side
type of assembly	screwable
application area	Device carrier
Recess for manufacturer	TE Connectivity: AMP Corning: FutureCom™ S1200 module Kat.7A Siemon: TERA® 4-Pair Outlet

Aluminium

Product	H	B	E1	E2	data jacks	G
UDEP-AMP 3	46 mm	75 mm	19,3 mm	14,6 mm	3	0,03 kg

H: height

B: width

E1: fitting dimension

E2: fitting dimension

data jacks: Maximum number of installable data jacks

G: weight

OPTIONAL ACCESSORIES

UGETD

